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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

- [1] (currently amended) A coating composition characterized by comprising: a polyalkylsilazane compound; an acetoxysilane compound; and an organic solvent.
- [2] (original) The coating composition according to claim 1, which further comprises a pore forming agent.
- [3] (original) The coating composition according to claim 2, wherein said pore forming agent is a copolymer comprising a siloxy-containing polyethylene oxide compound or a siloxy-containing polyethylene oxide compound as monomer units.
- [4] (currently amended) The coating composition according to any one of claims 1 to 3 claim 1, wherein said polyalkylsilazane compound comprises repeating units represented by general formula (1):

[Chemical formula 1]

$$\frac{\left\{\begin{pmatrix} R^{2} \\ N \end{pmatrix}_{p} \begin{pmatrix} R^{1} \\ N \end{pmatrix}_{r} \begin{pmatrix} R^{4} \\ N \end{pmatrix}_{r} \begin{pmatrix} R^{4} \\ N \end{pmatrix}_{q} \right\} (1)$$

wherein R¹ represents a hydrogen atom or an alkyl group having 1 to 3 carbon atoms, provided that all of R¹s of the whole compound do not simultaneously represent hydrogen;

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R² to R⁴ each independently represent a hydrogen atom or an alkyl group having 1

to 3 carbon atoms, provided that all of $\,{\,{\sf R}^2}$ to $\,{\sf R}^4$ do not simultaneously represent

hydrogen; and

p, q, and r each are 0 or 1 and $0 \le p + q + r \le 3$.

[5] (currently amended) A siliceous material characterized by being produced by

coating a coating composition according to any one of claims 1 to 4 claim 1 onto a

substrate or by filling a coating composition according to any one of claims 1 to 4 into a

frame or a groove, and firing the coating composition.

[6] (currently amended) A semiconductor device characterized by comprising a

siliceous material according to claim 5 as an intermetal dielectric.

[7] (currently amended) A process for producing a siliceous material, characterized

by comprising heating a coating composition according to any one of claims 1 to 4 claim 1

at a temperature of 350°C or below for 1 to 60 min.

[8] (new) The coating composition according to claim 1, wherein said

polyalkylsilazane compound further contains one or both groups represented by formulae

(2) and (3)

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$$\frac{\binom{R^8}{N} - \binom{R^9}{1}}{\binom{N}{N} - \binom{N}{1}} \qquad (3)$$

wherein R^5 to R^{11} each independently represent a hydrogen atom or an alkyl group having 1 to 3 carbon atoms, provided that both R^5 and R^6 do not simultaneously represent hydrogen and all of R^9 to R^{11} do not simultaneously represent hydrogen.